



## INTRODUCTION TO ELECTRONIC ASSEMBLY (DVD-32C)

**This test consists of twenty multiple-choice questions. All questions are from the video: *Introduction to Electronic Assembly (DVD-32C)*.**

**Each question has only one *most* correct answer. Circle the letter corresponding to your selection for each test item. If you wish to change an answer, erase your choice completely.**

**You should read through the questions and answer those you are sure of first. After your first pass through the test, then go back and answer the questions that you were not sure of. If two answers appear to be correct, pick the answer that seems to be the most correct response.**

**When you are finished, check to make sure you have answered all of the questions. Turn in the test materials to the instructor.**

**The passing grade for this test is 70% (14 correct answers or better).**

**Good luck!**



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Name \_\_\_\_\_ Date \_\_\_\_\_

- 1. Altering the flow of electricity is a job done by**
  - a. connectors
  - b. bare circuit boards
  - c. components
  - d. jumpers
  
- 2. The two types of component technologies are**
  - a. through-hole and surface mount
  - b. interfaces and interconnections
  - c. discrete and system
  - d. hard drives and RAM
  
- 3. Component placement is part of**
  - a. the wave soldering process
  - b. the reflow soldering process
  - c. through-hole assembly
  - d. surface mount assembly
  
- 4. The step prior to component placement is**
  - a. solder paste printing
  - b. wave soldering
  - c. reflow soldering
  - d. cleaning
  
- 5. The primary purpose of cleaning assemblies is to**
  - a. create the most beautiful assembly possible
  - b. remove flux residues
  - c. create better wetting of solder joints
  - d. all of the above
  
- 6. Conformal coating of assemblies is sometimes done to**
  - a. make them conform to other assemblies
  - b. make more stable mechanical connections
  - c. protect them from dust, dirt and moisture
  - d. bypass the burn-in process

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### 7. OEM stands for

- a. Ongoing Engineering Meetings
- b. Original Equipment Manufacturers
- c. Once Every Morning
- d. Organic Electronic Medium

### 8. EMS Providers provide

- a. services for other company's products
- b. designs for their own products
- c. manufacturing for their own products
- d. testing for their own products

### 9. In the electronics industry

- a. profit margins continue to decrease
- b. prices for computers and other products have decreased
- c. features and performance of computers and other products have increased
- d. all of the above

### 10. When there is any confusion about a job you're doing

- a. finish the job before asking a question
- b. always ask a question so you know the correct action to take
- c. immediately stop working and thoroughly read the appropriate manual
- d. priority must be given to meeting schedules

### 11. When working in electronics assembly, it's important to

- a. follow written instructions exactly
- b. pay careful attention to detail
- c. maintain a positive attitude
- d. all of the above

### 12. Teamwork is essential because

- a. it takes more than one person to replace a light bulb
- b. if one person isn't doing the job correctly, it affects the whole team
- c. members of the team need to compete against one another
- d. all of the above

### 13. Safety is the responsibility of

- a. everyone in the company
- b. government authorities
- c. the company safety officer
- d. the facilities manager

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- 14. Depending on your job, you may be asked to wear**
- a. a respirator
  - b. gloves
  - c. steel toed shoes
  - d. all of the above
- 15. A recent study indicated 40% of industrial injuries are due to**
- a. burns from wave soldering splashes
  - b. drugs and alcohol
  - c. not knowing how to evacuate the building in the event of an emergency
  - d. fighting on the job
- 16. Circuit boards should be handled by**
- a. the edges
  - b. the components
  - c. spreading your fingers across the board for the best grip possible
  - d. spring loaded pins
- 17. Components should be handled by**
- a. the leads
  - b. the adhesive
  - c. the body
  - d. any of the above
- 18. ESD stands for**
- a. Electronic Status Display
  - b. Engineering System Design
  - c. Evolutionary Silent Dynamic
  - d. Electrostatic Discharge
- 19. ESD prevention involves**
- a. wearing wrist and heel straps
  - b. working at grounded workstations
  - c. using static dissipative mats
  - d. all of the above
- 20. The biggest cause of scrap comes from**
- a. incorrect solder selection
  - b. incorrect component placement
  - c. improper handling
  - d. stencil misalignment